

Technical Data Sheet

MODEL NO: 190YG4 0603 Package 1.6*0.8mm Chip LEDs

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
GaP	Green	Water Clear

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Luminous Intensity	I	IF=20mA		10		mcd
Dominant Wavelength	λD	IF=20mA		570		nm
Peak Emission Wavelength	λр	IF=20mA				nm
Viewing Angle	2 🖯 1/2	IF=20mA		120		Deg
Forward Voltage	VF	IF=20mA		2.2	2.4	V
Reverse Current	IR	VR=5V			10	μA

Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Maximum	Unit
Power Dissipation	Pd	78	mW
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse Width)	IF(Peak)	100	mA
Continuous Forward Current	IF	30	mA
Reverse Voltage	VR	5	V
Derating Linear From 25℃		0.3	mA/°C
Operating Temperature Range	Topr	-30 to +80	°C
Storage Temperature Range	Tstg	-40 to +90	$^{\circ}\!\mathbb{C}$

2015MAR16W



Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

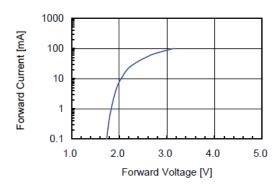


Fig 2. Relative Intensity vs. Forward Current

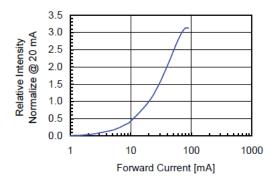


Fig 3. Forward Voltage vs. Temperature

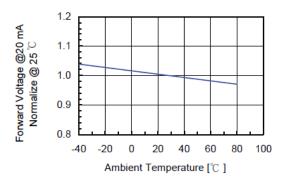


Fig 4. Relative Intensity vs. Temperature

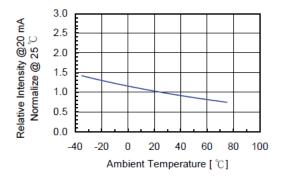
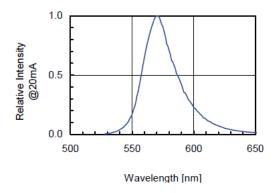
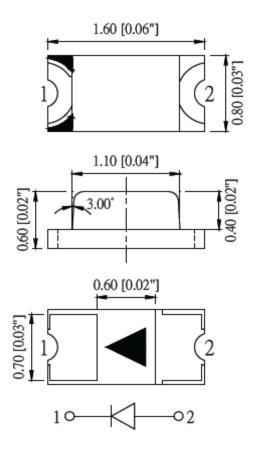


Fig 5. Relative Intensity vs. Wavelength

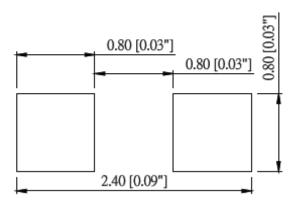




PACKAGE DIEMENSION

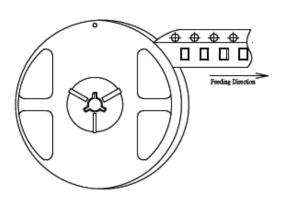


Recommend Pad Layout

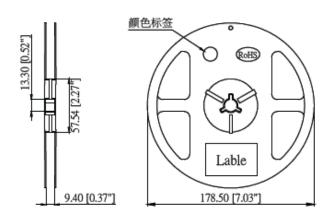




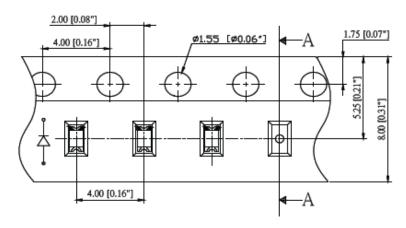
Feeding Direction

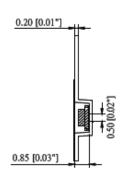


Dimensions of Reel (Unit: mm)

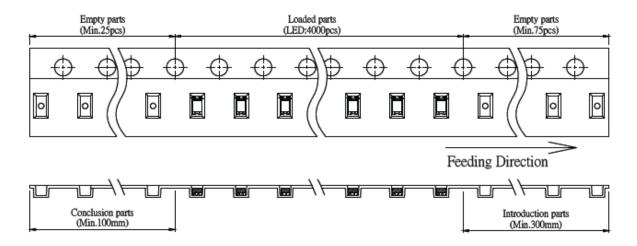


Dimensions of Tape (Unit: mm)





Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
- 4. 4,000 pcs/Reel.

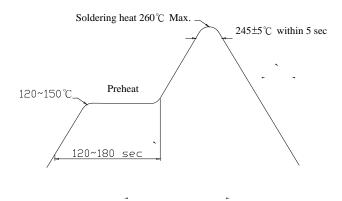


Descriptions :

- The Chip-LED Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature application, etc.

Soldering heat reliability (DIP):

Please refer to the following figure:



Precautions For Use :

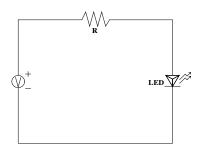
• Over – current – proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

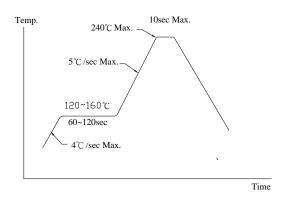
- Storage
- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60° R.H. Max..
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.



● Test Circuit



Reflow Temp. / Time :



Reliability Test Items And Conditions

The reliability of products shal be satisfied with items listed below.

No.	Items	Test Condition	Test Hours/Cycles	Sample Size
1	Solder Heat	TEMP : 260°C±5°C	5 sec	48 pcs
2	Temperature Cycle	90°C ~ 25°C ~ -30°C ~ 25°C 30m 5m 30m 5m	300Cycles	48 Pcs
3	Thermal Shick	100°C ~ -55°C 10m 10m	100Cycles	48 Pcs
4	Operation Life	If=20mA	1000 Hrs	48 Pcs
5	High Temperature Storage	Temp:90°C	1000Hrs	48 Pcs
6	Low Temperature Storage	Temp:-30°C	1000Hrs	48 Pcs
7	High Temperature/High Humidity	80°C / R.H80%	1000Hrs	48 Pcs